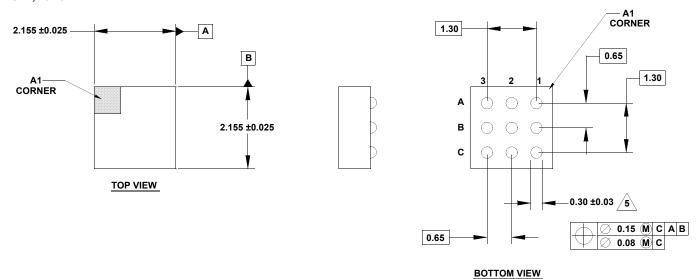
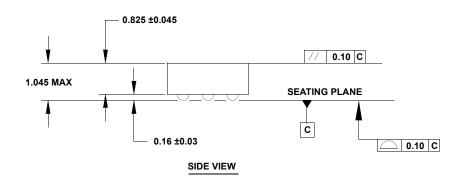
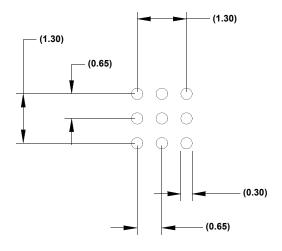
## **Package Outline Drawing**

\$3x3.9
3X3 ARRAY 9 BUMP OPTICAL CHIP SCALE PACKAGE (OCSP)
Rev 7, 10/10







TYPICAL RECOMMENDED LAND PATTERN

## NOTES:

- Dimensions are in millimeters.
   Dimensions in ( ) for Reference only.
- 2. Dimensioning and tolerancing conform to ASME Y 14.5M-1994
- 3. Primary datum C and seating plane are defined by the spherical crowns of the contact balls.
- 4. Pin "A1" is marked on the top and bottom side adjacent to the A1 ball.
- 5. Dimension is measured at the maximum ball diameter.

